

CLAIMS

What is claimed is:

1. An improvement on white light LED, which is composed of an electrode support,
LED emitting chips, a fluorescent powder layer, a diffusion layer and packaging
5 resin, wherein the process includes placing LED emitting chips on electrode
support, followed by dispensing gel material to form a fluorescent powder layer
that covers LED emitting chips, finally followed by using packaging resin for
encapsulation; and the process has a feature that uses the diffusion layer
containing transparent microparticles makes LED emitted light more uniform
10 through light refraction.
2. The improvement on white light LED of claim 1, wherein the material of the
transparent microparticles contained in the diffusion layer is inorganic glass
powder (SiO_2) or polymeric material such as PMMA, PC, PE and PET.
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